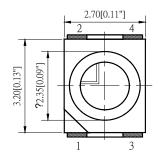
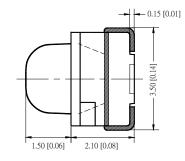
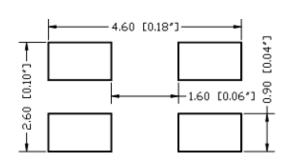


# SPECIFICATION CSPD1311Y3C

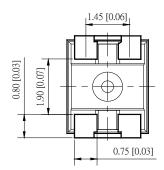
## **PACKAGE OUTLINES**

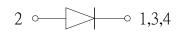






RECOMMENDED PAD LAYOUT





#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSPD1311Y3C	InGaAIP	Yellow	Water Clear	30°	





## **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	50	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	145	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 10 sec Max		

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

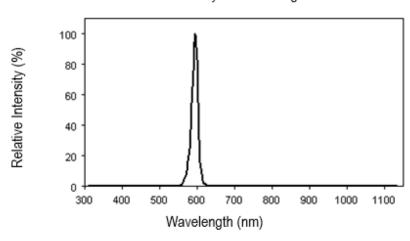
Darameter	Symbol	Toot Condition	Value			Llmit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 50mA	6800	13000	1	mcd
Forward Voltage	VF	IF = 50mA	-	2.3	2.9	V
Reverse Leakage Current	lR	VR = 5V	ı	10	ı	μΑ
Viewing Angle at 50% Iv	201/2	IF = 50mA	-	30	ı	Deg
Peak Wavelength	λР	IF = 50mA	-	595	-	nm
Dominant Wavelength	λD	IF = 50mA	585	592	595	nm

<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.

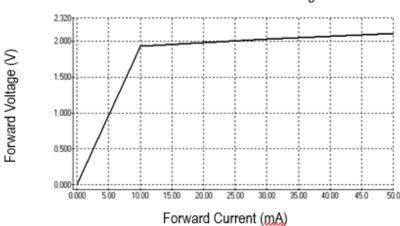


## **OPTICAL CHARACTERISTIC CURVES**

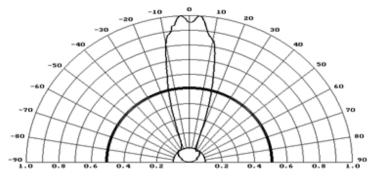
### Relative Intensity vs. Wavelength



### Forward Current vs. Forward Voltage



#### Directive Characteristics

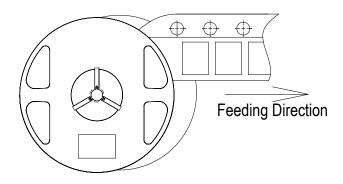


RoHS Compliant

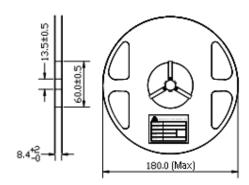


## **PACKAGING SPECIFICATION**

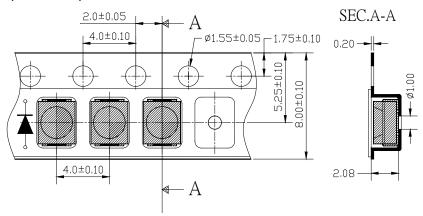
### **Feeding Direction**



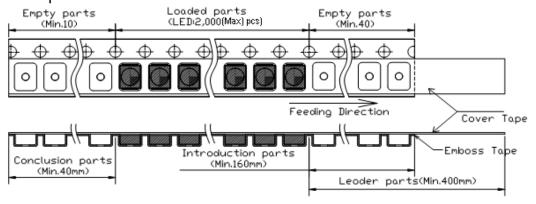
### Dimensions of Reel (Unit: mm



### Dimensions of Tape (Unit: mm)



### Arrangement of Tape



#### Notes:

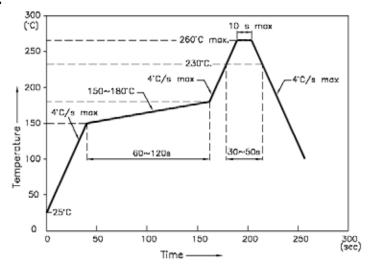
- 1. Empty component pockets are sealed with top cover tape.
- 2. The maximum number of missing lamp is two.
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 2,000 pcs/Reel





## **SOLDERING CONDITIONS**

#### REFLOW PROFILE



#### Notes:

- 1. We recommend reflow temperature 245°C ( $\pm 5$ °C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not cause stress to epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.
- Soldering Iron

Basic spec is  $\leq$  5 sec when 260°C. If temperature is higher, time should be shorter (+10°C $\rightarrow$ -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of device should be under 230°C.

#### Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of the iron cannot touch copper foil.
- 3. Twin-head type is preferred

